

- 1-4. (Cancelled)
5. (Previously Presented) A cooling assembly comprising:
an electronic package having a cavity;
at least one die with active electronics components mounted using compliant interconnects within the cavity; and
at least one coolant port that allows a coolant to enter the cavity and directly cool the active electronic components of each die,
wherein the compliant interconnects are coupled between each die and the package,
wherein said compliant interconnects comprise spring contacts, and
wherein said spring contacts comprise lithographic springs.
6. (Original) The cooling assembly of claim 5, wherein said lithographic springs comprise multipart lithographic springs.

7. (Previously Presented) A cooling assembly comprising:
an electronic package having a cavity;
at least one die with active electronic components mounted using compliant interconnects within the cavity; and
at least one coolant port that allows a coolant to enter the cavity and directly cool the active electronic components of each die,
wherein the compliant interconnects are coupled between each die and the package,
and
wherein each die has at least one active surface, and when the coolant circulates in the cavity the coolant directly cools each active surface of each die.

8. (Previously Presented) A cooling assembly comprising:
an electronic package having a cavity;
at least one die with active electronic components mounted using compliant interconnects within the cavity; and
at least one coolant port that allows a coolant to enter the cavity and directly cool the active electronic components of each die,
wherein the compliant interconnects are coupled between each die and the package,
and
wherein each die has a plurality of surfaces within the cavity including at least one active surface associated with respective active electronic components, and when the coolant circulates in the cavity the coolant directly cools each surface of each die, thereby reducing thermal gradients or hot spots on each active surface of each die and increasing the operating range of each die.

9-15. (Cancelled)

16. (Previously Presented) A cooling assembly comprising:
an electronic package having a cavity;
at least one die with active electronic components mounted using compliant interconnects within the cavity; and
at least one coolant port that allows a coolant to enter the cavity and directly cool the active electronic components of each die,
wherein the compliant interconnects are coupled between each die and the package,
and
wherein said package further comprises a bottom substrate on one side of the cavity, wherein each die with active electronic components is connected to the bottom substrate by the compliant interconnects, and wherein the active electronic components face the bottom substrate and contact coolant surrounding the compliant interconnects within the cavity.

17. (Original) The cooling assembly of claim 16, wherein said compliant interconnects comprise first and second sets of compliant interconnects and wherein said package further comprises a top substrate; and
further comprising alignment posts wherein the alignment posts are attached to the bottom substrate, the first set of compliant interconnects is coupled between each die and the bottom substrate, and the dies are further held in place by contact with the alignment posts and downward pressure from the second set of compliant interconnects.

18-19. (Cancelled)

20. (Previously Presented) A cooling assembly comprising:
an electronic package having a cavity;
at least one die with active electronic components mounted using compliant interconnects within the cavity; and

at least one coolant port that allows a coolant to enter the cavity and directly cool the active electronic components of each die,

wherein the compliant interconnects are coupled between each die and the package,
and

wherein said package further comprises a top substrate with a top surface representing an exterior surface of the package and wherein the top surface includes contacts, whereby external components can be electrically coupled to each die via the contacts.

21. (Previously Presented) A cooling assembly comprising:

an electronic package having a cavity;

at least one die with active electronic components mounted using compliant interconnects within the cavity; and

at least one coolant port that allows a coolant to enter the cavity and directly cool the active electronic components of each die,

wherein the compliant interconnects are coupled between each die and the package,
and

wherein said package further comprises:

a top substrate;

a bottom substrate; and

interconnection elements that provide electrical paths extending through the top substrate and the bottom substrate.

22. (Cancelled)

23. (Previously Presented) A cooling assembly comprising;

an electronic package having a cavity; and

at least one die with active electronic components mounted using compliant interconnects within the cavity;

at least one coolant port that allows a coolant to enter the cavity and directly cool the active electronic components of each die,

wherein the compliant interconnects are coupled between each die and the package;
and

a coolant circulation system coupled to said at least one coolant port, wherein the coolant circulates within the package and directly contacts all surfaces of each die to directly cool active electronic components during their operation.

24. (Previously Presented) A cooling assembly comprising:

an electronic package having a cavity;

at least one die with active electronic components mounted using compliant interconnects within the cavity; and

at least one coolant port that allows a coolant to enter the cavity and directly cool the active electronic components of each die,

wherein the compliant interconnects are coupled between each die and the package;

a cooling member; and

one or more heat radiators, wherein each die is immersed in the coolant and each heat radiator transfers heat generated by each die from the coolant to said cooling member.

25. (Previously Presented) A cooling assembly comprising;

an electronic package having a cavity;

at least one die with active electronic components mounted using compliant interconnects within the cavity; and

at least one coolant port that allows a coolant to enter the cavity and directly cool the active electronics components of each die,

wherein the compliant interconnects are coupled between each die and the package;
and
at least one non-contacting compliant interconnect coupled to a surface of said at
least one die, whereby, heat can be further directed away from the surface of a die.

26. (Previously Presented) A cooling assembly comprising:
an electronic package having a cavity;
at least one die with active electronic components mounted using compliant
interconnects within the cavity; and
at least one coolant port that allows a coolant to enter the cavity and directly cool the
electronic components of each die,
wherein the compliant interconnects are coupled between each die and the package,
and
wherein said package further comprises:
a top substrate; and
a bottom substrate,
wherein each die is flip-chip bonded to said top substrate.

27-31. (Cancelled)